

# KDT, micro-nanoelectronics; Finnish viewpoints

- Material studies:
  - Black silicon
  - RF materials and components
- Physical and functional integration
  - Packaging: different sensor technologies, photonics, MEMS etc in same device
  - AI and sensor fusion, data analysis
  - Flexible constructions, sustainable manufacturing
- SoC technology
  - AI algorithms
  - Low power processing
- Quantum components
- Application areas
  - Telecommunication
  - Industrial control
  - Medical devices
  - Autonomous vehicles and machines